

Refine Search

Search Results -

Terms	Documents
(under adj bump adj metalization) and (copper same nickel same titanium same wetting)	0

Database:

- US Pre-Grant Publication Full-Text Database
- US Patents Full-Text Database
- US OCR Full-Text Database
- EPO Abstracts Database
- JPO Abstracts Database
- Derwent World Patents Index
- IBM Technical Disclosure Bulletins

Search:

L6

Refine Search

Recall Text

Clear

Interrupt

Search History

DATE: Monday, April 10, 2006 Printable Copy Create Case

Set Name Query	Hit Count	Set Name
side by side		result set
DB=JPAB; PLUR=YES; OP=ADJ		
L6 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	0	L6
DB=EPAB; PLUR=YES; OP=ADJ		
L5 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	0	L5
DB=PGPB; PLUR=YES; OP=ADJ		
L4 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	9	L4
DB=TDBD; PLUR=YES; OP=ADJ		
L3 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	0	L3
DB=DWPI; PLUR=YES; OP=ADJ		
L2 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	0	L2
DB=USPT; PLUR=YES; OP=ADJ		
L1 (under adj bump adj metalization) and (copper same nickel same titanium same wetting)	5	L1

END OF SEARCH HISTORY